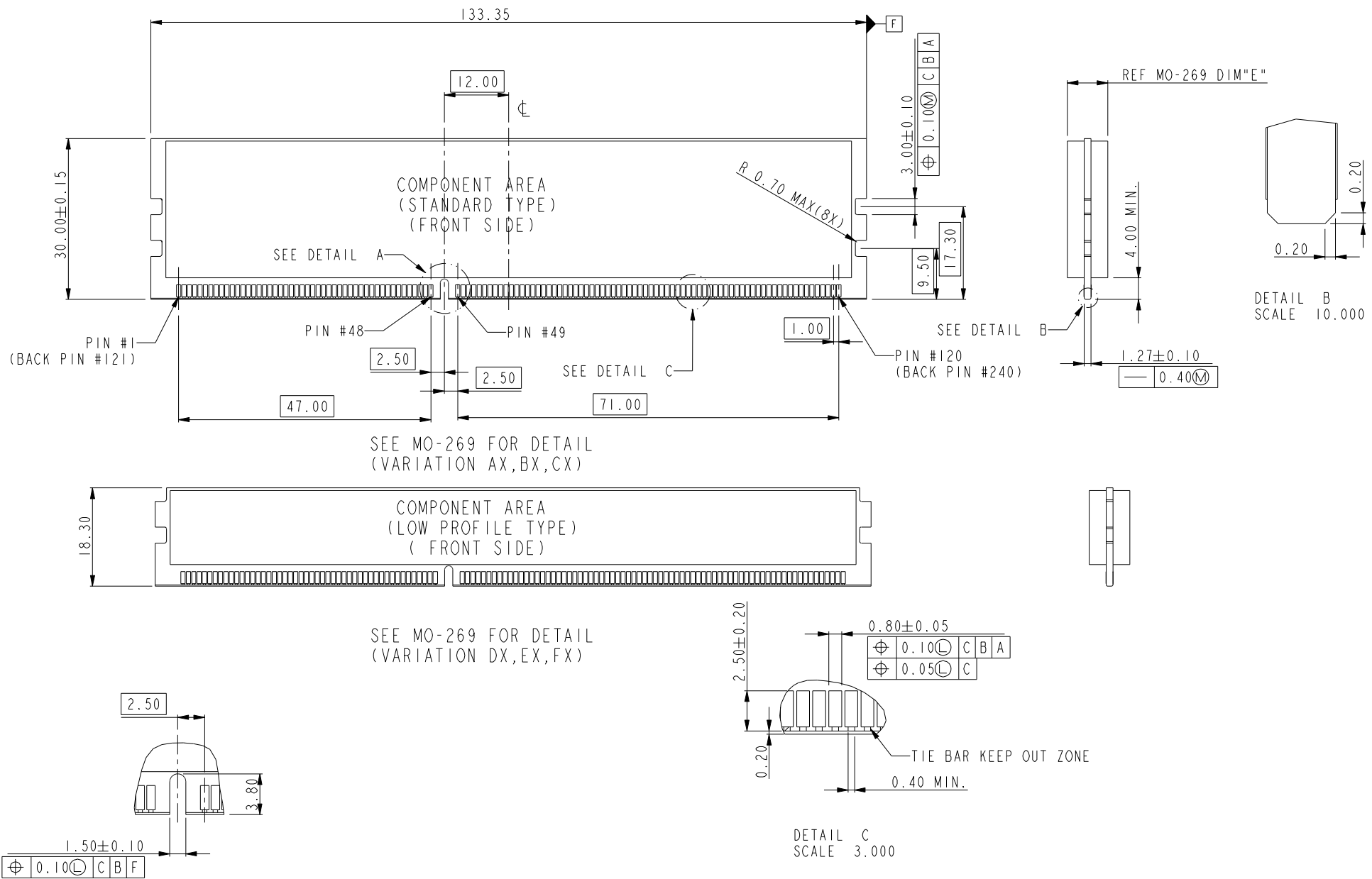






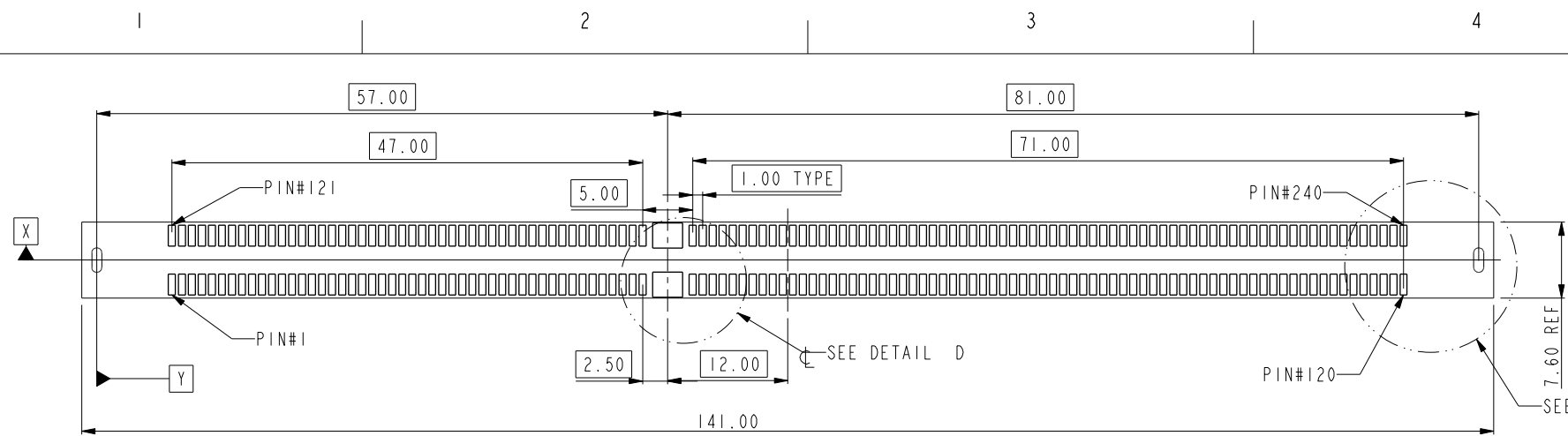
Copyright FCI.



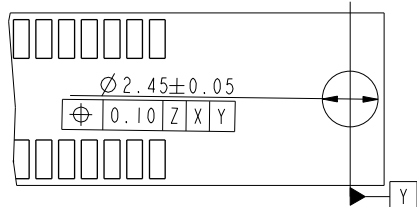
	title		SMT DDRIII SOCKET ASS'Y		dwg no	10079248	Rev. M
			DDRII, 240P SOCKET(FOR RDIMM MODULE)				
	catalog no		*		CUSTOMER		sheet 2 of 4



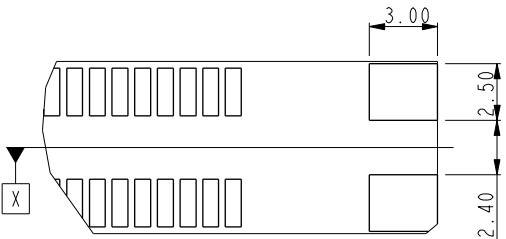
Copyright FCI.



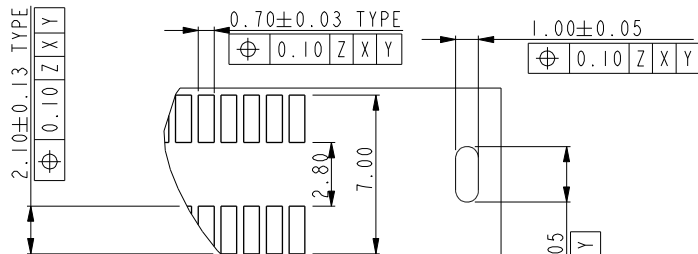
### RECOMMEND CIRCUIT BOARD LAYOUT



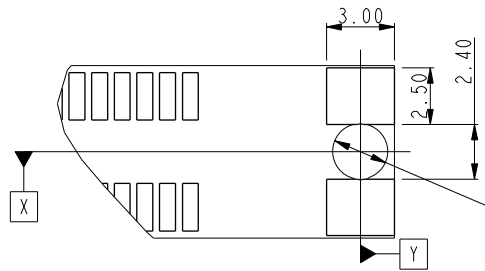
DETAIL E  
SCALE 3.000  
Standard hole for  
hold-down clips



DETAIL E  
SCALE 3.000  
For smt holddown type

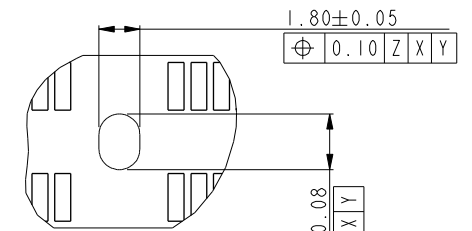


DETAIL E  
SCALE 3.000  
For paste-in-hole applications.  
Can be used to solder clips  
during reflow operation.

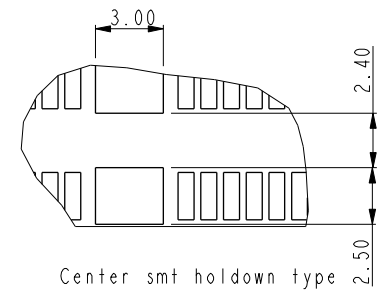


DETAIL E  
SCALE 3.000

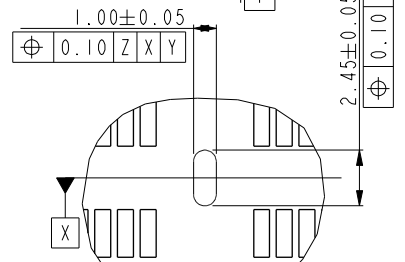
For 3smt holddown + 2plastic post type



Center post type  
DETAIL D  
SCALE 3.000



Center smt holddown type  
DETAIL D  
SCALE 3.000



Center forklock type  
DETAIL D  
SCALE 3.000



title	SMT DDRIII SOCKET ASS'Y
	DDRII,240P SOCKET(FOR RDIMM MODULE)
catalog no	*

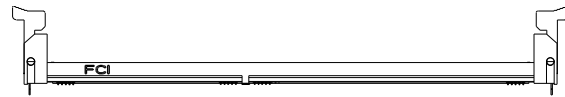
dwg no	10079248
CUSTOMER	

Rev.  
M

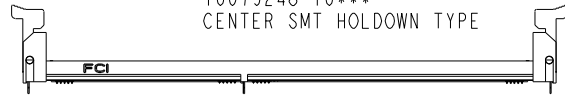
sheet 3 of 4



Copyright FCI.



SCALE 0.500



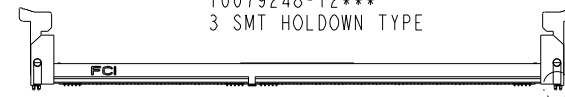
10079248-10\*\*\*  
CENTER SMT HOLDOWN TYPE

SCALE 0.500



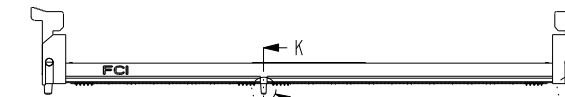
10079248-11\*\*\*  
3 FORK LOCK TYPE

SCALE 0.500



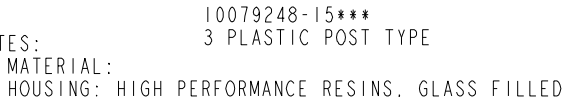
10079248-12\*\*\*  
3 SMT HOLDOWN TYPE

SCALE 0.500



10079248-13\*\*\*  
3 SMT HOLDOWN AND 2 PLASTIC POST TYPE

SCALE 0.500



10079248-15\*\*\*  
3 PLASTIC POST TYPE

#### NOTES:

1. MATERIAL:  
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.  
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.  
TERMINAL: HIGH PERFORMANCE COPPER ALLOY  
METAL CLIP: COPPER ALLOY.
2. FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-486.
4. PACKAGING SPECIFICATION: GS-14-899.
5. RECOMMENDED STENCIL THICKNESS NO LESS THAN 0.15 mm.
6. FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
7. THE DATE CODE IS SHOWN "MMDDYY\*". "\*" MEANS PRODUCTION LINE.
8. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
9. THE HOUSING WILL WITH STAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN AN IR REFLOW SOLDERING APPLICATION.
10. PRODUCT APPLICATION SPEC GS-20-089.
11. THE HOLDOWN TYPES ARE OPTION FOR HOLDOWN OR FORKLOCK.

STYLE : MECHANICAL KEYING

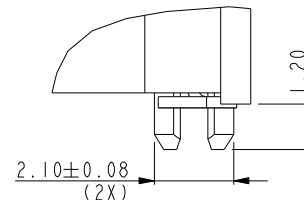
1 : 1.5 VOLT. W/ CENTER KEY

HOLD DOWN TYPE

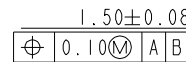
- 0 : CENTER HOLD DOWN, FORKLOCK AT BOTH END  
1 : 3 FORKLOCK TYPE  
2 : 3 SMT HOLDOWN TYPE  
3 : 3 SMT HOLDOWN AND 2 PLASTIC POST  
5 : 3 PLASTIC POST TYPE

PACKAGE AND MYLAR OPTION

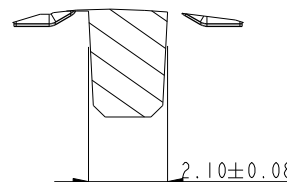
- 0 : SOFT TRAY WITHOUT MYLAR  
1 : HARD TRAY WITH MYLAR  
2 : HARD TRAY WITHOUT MYLAR  
3 : SOFT TRAY WITH MYLAR



DETAIL N  
SCALE 5.000



DETAIL J  
SCALE 5.000



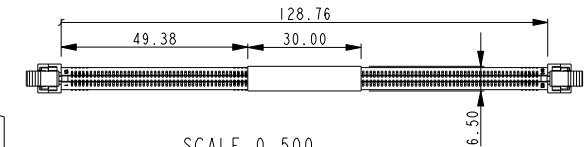
SECTION K-K  
SCALE 5.000

PLATING

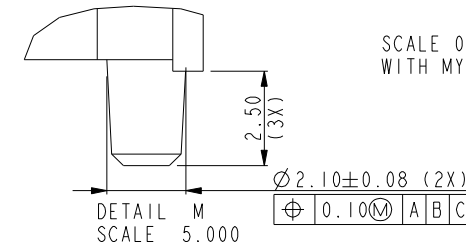
CODE	CONTACT	SOLDERTAIL	UNDERPLATE	NOTE
1	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. TIN-LEAD	50u" (1.27um) MIN. NICKEL OVERALL	CONTACT NON-LUBRICANT
2	15u" (0.38um) MIN. GOLD			
3	30u" (0.76um) MIN. GOLD			
4	GOLD FLASH			
5	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. 100% MATT TIN	50u" (1.27um) MIN. NICKEL OVERALL	CONTACT LUBRICATED
6	15u" (0.38um) MIN. GOLD			
7	30u" (0.76um) MIN. GOLD			
8	GOLD FLASH			
1LF	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. 100% MATT TIN	50u" (1.27um) MIN. NICKEL OVERALL	CONTACT NON-LUBRICANT
2LF	15u" (0.38um) MIN. GOLD			
3LF	30u" (0.76um) MIN. GOLD			
4LF	GOLD FLASH			
5LF	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. 100% MATT TIN	50u" (1.27um) MIN. NICKEL OVERALL	CONTACT LUBRICATED
6LF	15u" (0.38um) MIN. GOLD			
7LF	30u" (0.76um) MIN. GOLD			
8LF	GOLD FLASH			

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR  
1 : BLACK HOUSING + BLACK EJECTOR  
2 : BLACK HOUSING + BLUE(661C) EJECTOR  
3 : BLACK HOUSING + YELLOW(123C) EJECTOR



SCALE 0.500  
WITH MYLAR TAPE (OPTIONAL)



DETAIL M  
SCALE 5.000



title SMT DDRIII SOCKET ASS'Y  
DDRIII, 240P SOCKET(FOR RDIMM MODULE)  
catalog no \*

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CUSTOMER

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